



# THCV2712

V-by-One® HS Distributor

## General Description

The THCV2712 is a high performance 1:2 signal distributor for V-by-One® HS with data rates up to 4Gbps and integrated 2:1 and 1:2 signal switcher support bi-directional communication.

The THCV2712 features the distribution function which duplicates a V-by-One® HS signal and the switch function which changes the path of signals. All configurations are supported by external pins.

All driver outputs and receiver inputs are internally terminated which no require external components.

## Features

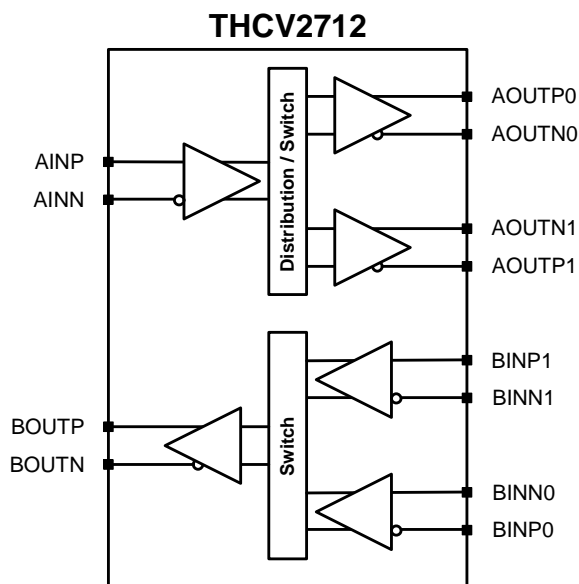
- Unidirectional Distribution
- Bi-directional Switch (1:2 and 2:1)
- Transmit VOD Control : 600 to 1300 mVp-p
- Available in single supply voltage 3.3V with integrated LDO
- ESD: HBM ±4kV
- QFN40 (5.0mm x 5.0mm)

## Applications

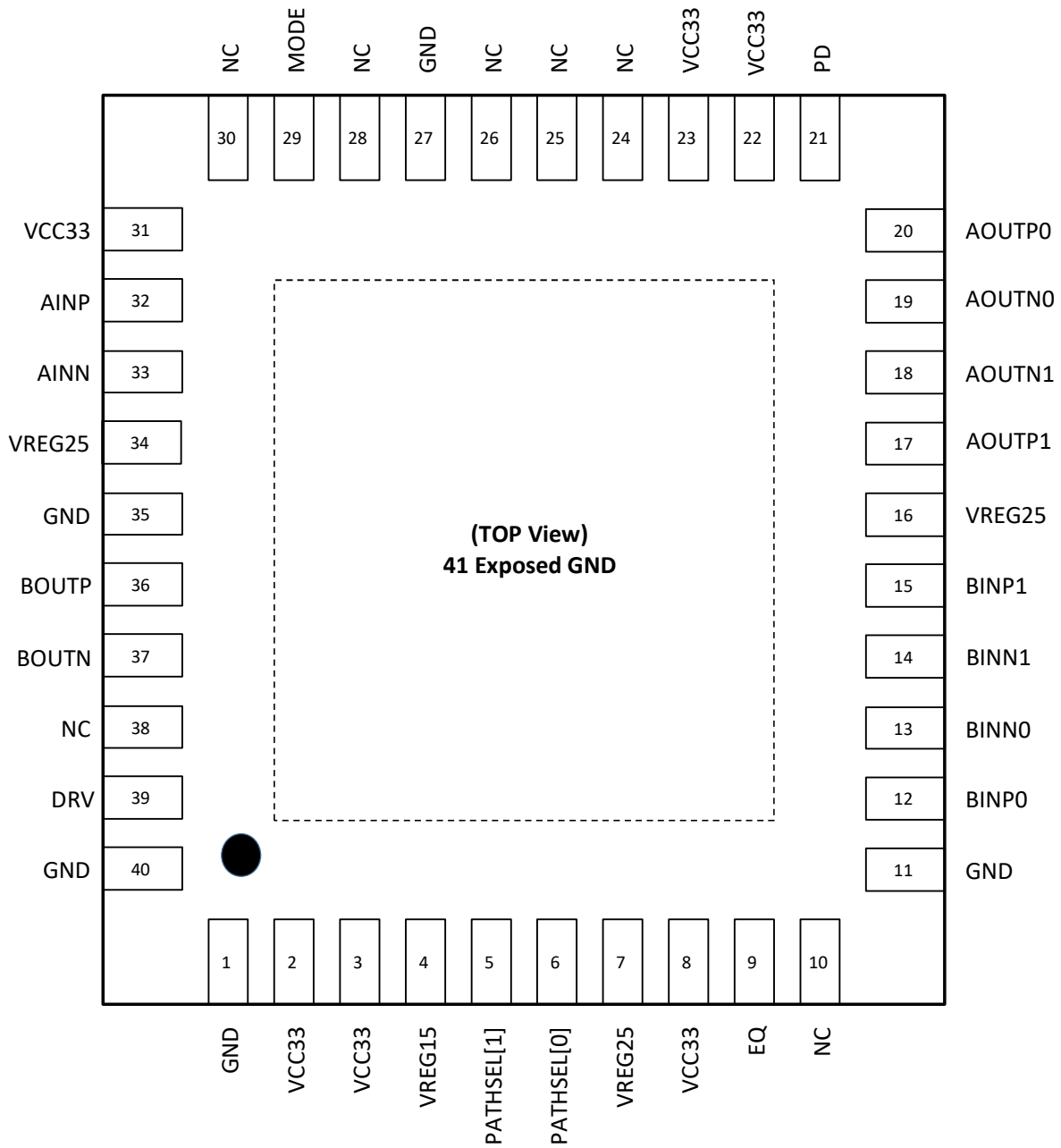
All V-by-One® HS applications such as

- Digital Signage
- Digital Blackboard
- Multi-Function Printer
- Production Printer
- Medical Imaging
- Machine Vision
- Image Sensor
- Camera

## Block Diagram



**Pin Configuration**



### Pin Description

Pin Name	Pin No	Type	Description
AINP	32	CI	High-Speed CML Channel A (CHA) Signal Input
AINN	33	CI	High-Speed CML Channel A (CHA) Signal Input
BOUTP	36	CO	High-Speed CML Channel B (CHB) Signal Output
BOUTN	37	CO	High-Speed CML Channel B (CHB) Signal Output
AOUTP1	17	CO	High-Speed CML Port 1 of CHA Signal Output
AOUTN1	18	CO	High-Speed CML Port 1 of CHA Signal Output
AOUTP0	20	CO	High-Speed CML Port 0 of CHA Signal Output
AOUTN0	19	CO	High-Speed CML Port 0 of CHA Signal Output
BINP1	15	CI	High-Speed CML Port 1 of CHB Signal Input
BINN1	14	CI	High-Speed CML Port 1 of CHB Signal Input
BINP0	12	CI	High-Speed CML Port 0 of CHB Signal Input
BINN0	13	CI	High-Speed CML Port 0 of CHB Signal Input
PD	21	I	Power Down 0: Operation 1: Chip Power Down
MODE	29	I	Mode select 0 : Distribution 1 : Switch
PATHSEL[1:0]	5,6	I	Select Switch Input / Output
EQ	9	3LI	Rx equalizer setting.
DRV	39	3LI	Tx output swing control
VREG15	4	PWR	Decoupling Capacitor Pin for On-chip Regulator.
VREG25	7,16,34	PWR	Decoupling Capacitor Pin, 2.5V output.
VCC33	2,3,8,22, 23,31	PWR	Power supply pin for on-chip regulator.
GND	1,11,27, 35,40,41	GND	Ground. Must be tied to the PCB ground plane through an array of vias. Pin#41 is exposed pad ground.
NC	10,24,25, 26,28,30, 38	NC	Non-connection pin. Must be open.

CI: CML Input buffer, CO: CML Output buffer

I: LVCMOS Input buffer, 3LI: 3-Level LVCMOS Input buffer,

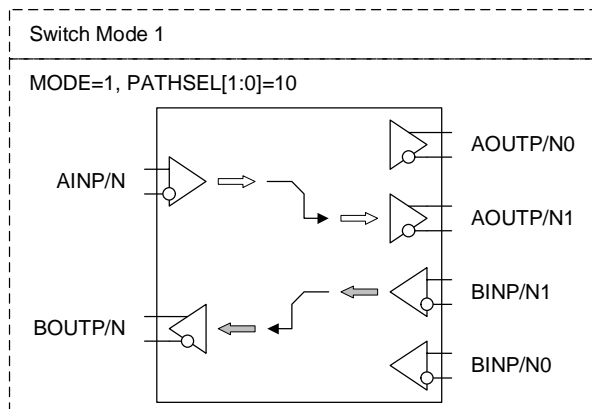
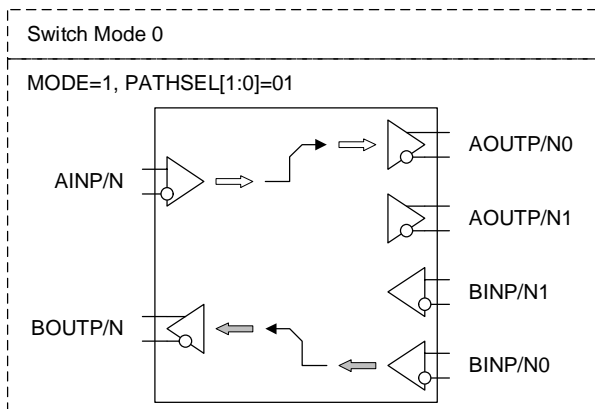
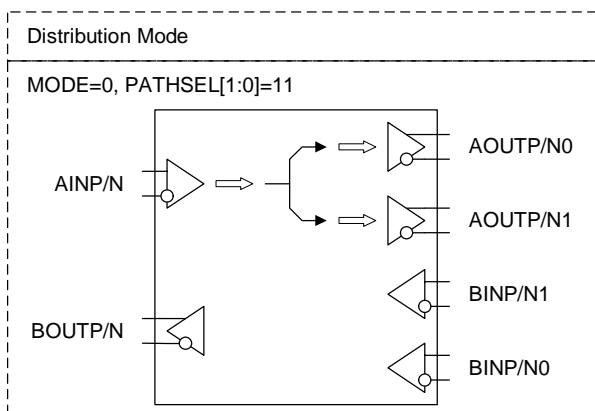
PWR: Power supply, GND: Ground, NC: Non-connection pin

**Operation Mode Settings**

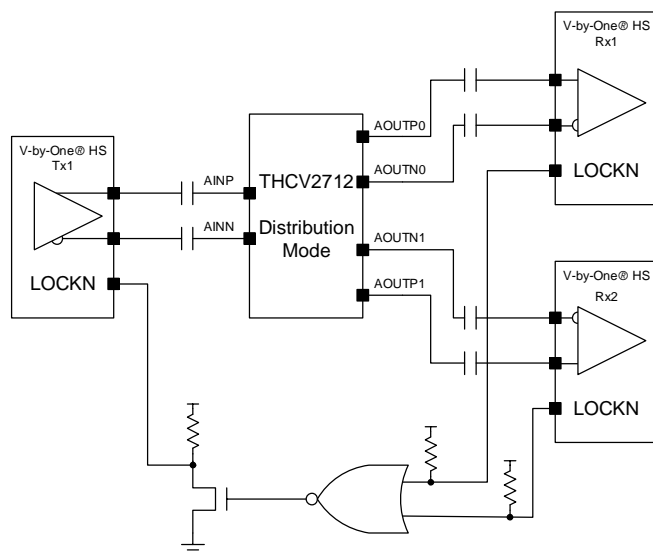
Table1 shows the operation mode setting.

**Table 1. Operation Mode Setting**

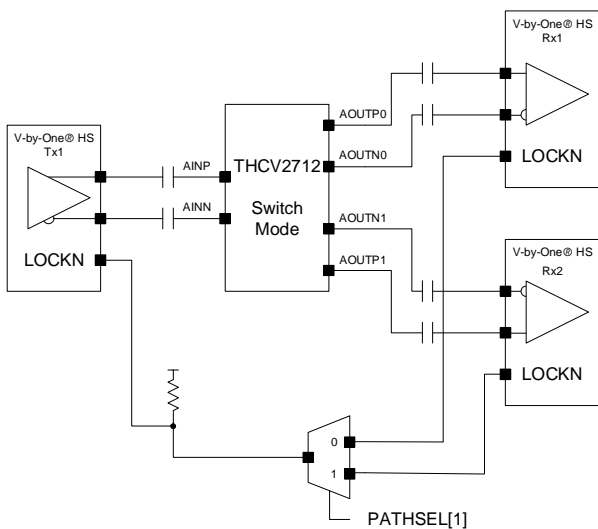
Pin Settings			Operation Mode
PD	MODE	PATHSEL[1:0]	
0	0	11	Distribution Mode
	1	01	Switch Mode Port 0 Enable
		10	Switch Mode Port 1 Enable
1	Ignore	Ignore	Chip Power Down.



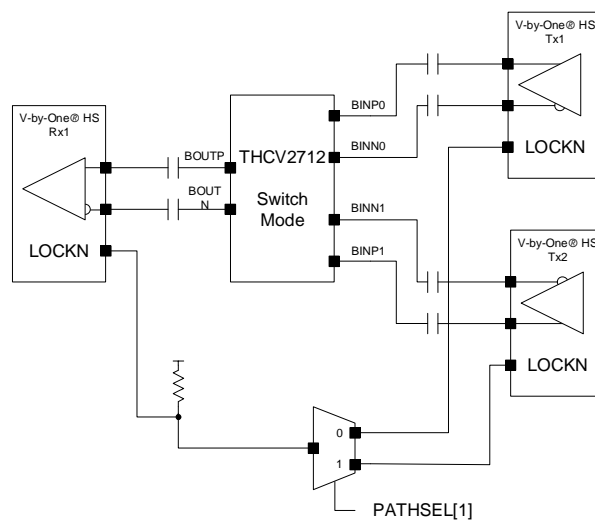
LOCKN/HTPDN signals are not be distributed and switched. The signals should be bypassed THCV2712.



**Figure 1. LOCKN circuits in Distribution Mode**



(a) 1:2 Switch Function



(b) 2:1 Switch Function

**Figure 2. LOCKN circuits in Switch Mode**

## Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings

Parameter	Min	Typ	Max	Unit
Supply Voltage(VCC33)	-0.3	-	4.0	V
LVC MOS Input Voltage	-0.3	-	VCC33+0.3	V
Level Control LVC MOS Input Voltage	-0.3	-	VCC33+2.5	V
3-Level LVC MOS Input Voltage	-0.3	-	VCC33+0.3	V
CML Receiver Input Voltage	-0.3	-	3.0	V
CML Transmitter Output Voltage	-0.3	-	3.0	V
ESD Rating	HBM	-	±4	kV
	CDM	-	±500	V
Storage Temperature	-55	-	125	°C
Junction Temperature	-	-	125	°C
Reflow Peak Temperature/Time	-	-	260/10	°C/sec

## Recommended Operating Conditions

Table 3. Recommended Operating Condition

Parameter	Min	Typ	Max	Unit
Supply Voltage(VCC33)	3.0	3.3	3.6	V
Supply Ramp Requirement	0.1	-	50	ms
Operating Temperature	-40	-	85	°C

**Electrical Specification**

LVC MOS DC Specification

**Table 4. LVC MOS DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
VIH	High Level Input Voltage	-	2.0	-	VCC33	V
VIL	Low Level Input Voltage	-	0	-	0.7	V
VOH	High Level Output Voltage	I <sub>oh</sub> =-2mA	2.4	-	VCC33	V
VOL	Low Level Output Voltage	I <sub>ol</sub> =8mA	0	-	0.4	V
IOZH	Output Leak Current High in Hi-Z State	-	-15	-	15	uA
IOZL	Output Leak Current Low in Hi-Z State	-	-15	-	15	uA

3-Level LVC MOS DC Specification

**Table 5. 3-Level LVC MOS DC Specification**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>THL</sub>	Low-Level Threshold Voltage	*	0.42	0.83	1.25	V
V <sub>THH</sub>	High-Level Threshold Voltage	*	1.25	1.67	2.08	V
I <sub>IH_3L</sub>	High Level Input Leak Current	VIN=VCC33	-100	-	100	uA
I <sub>IL_3L</sub>	Low Level Input Leak Current	VIN=GND	-100	-	100	uA

\*Must be tied for setting each level

Low: Tie 1kΩ ±5% to GND

Float: Leave pin open

High: Tie 1kΩ ±5% to VCC33

Supply Current

**Table 6. Supply Current**

Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
ICCW	Active Mode Supply Current	PD=0,MODE=1 EQ=High DRV=High	-	-	170	mA
		PD=0,MODE=1 EQ=Low DRV=Low	-	90	-	mA
		PD=0,MODE=0	-	-	250	mA
ICCS	Power Down Supply Current	PD=1	-	1.0	2.0	mA

Receiver DC/AC Specification

**Table 7. Receiver DC/AC Specification**

Over recommended operating supply and temperature range unless otherwise specified

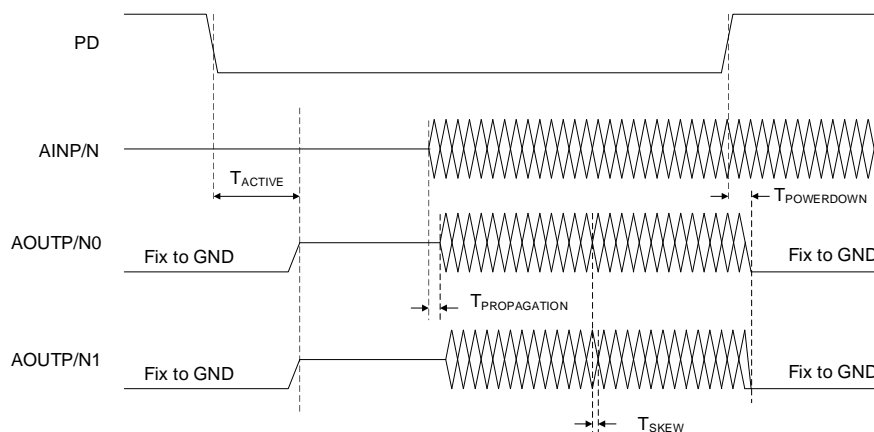
Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>RX-TH</sub>	CML Differential Input High Threshold		-	-	50	mV
V <sub>RX-TL</sub>	CML Differential Input Low Threshold		-50	-	-	mV
V <sub>RX-RIN</sub>	CML Differential Input Resistance		80	100	120	Ω
V <sub>RX-EQ-LOW</sub>	Input Equalization@2GHz	EQ=Low	-	3.2	-	dB
V <sub>RX-EQ-FLOAT</sub>	Input Equalization@2GHz	EQ=Float	-	4.6	-	dB
V <sub>RX-EQ-HIGH</sub>	Input Equalization@2GHz	EQ=High	-	7.6	-	dB

Transmitter DC / AC specifications

**Table 8. Transmitter DC / AC specification**

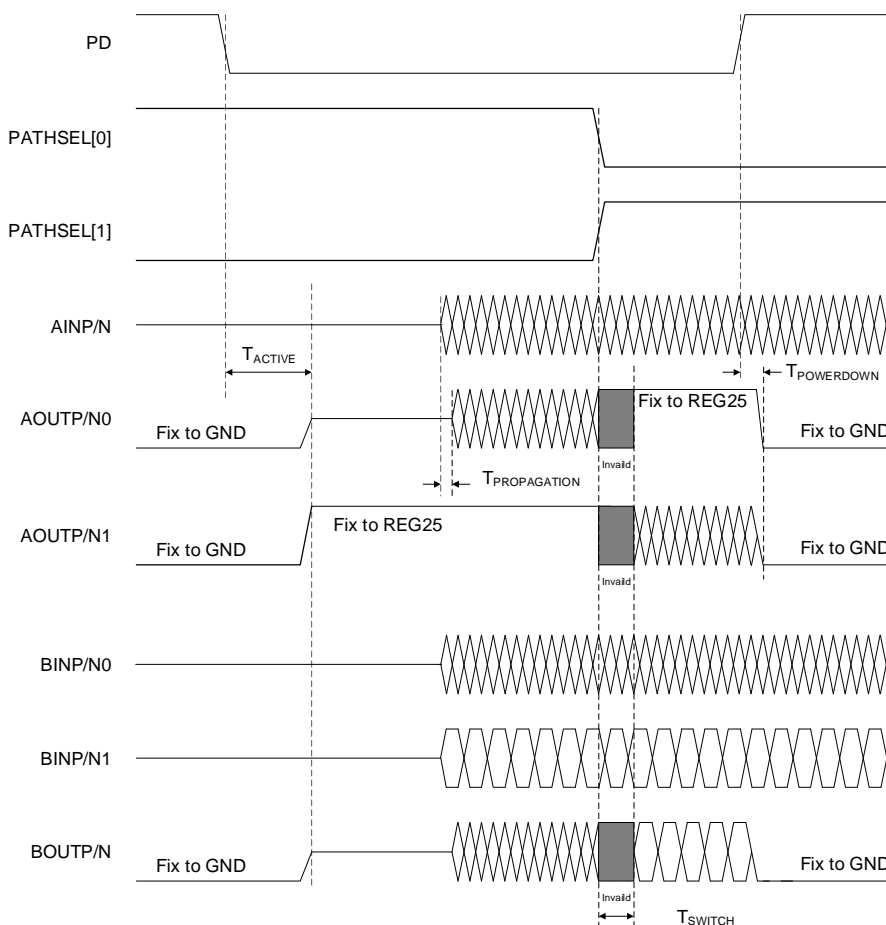
Over recommended operating supply and temperature range unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V <sub>TX-DIFF-PP-LOW</sub>	Differential p-p Tx Voltage Swing	DRV=Low	0.4	0.6	0.8	V
V <sub>TX-DIFF-PP-FLOQT</sub>	Differential p-p Tx Voltage Swing	DRV=Float	0.8	1.0	1.2	
V <sub>TX-DIFF-PP-HIGH</sub>	Differential p-p Tx Voltage Swing	DRV=High	1.0	1.3	1.6	
R <sub>TX-DIFF-DC</sub>	DC Differential Impedance	-	80	100	120	Ω
V <sub>TX-DC-CM</sub>	Transmitter DC Common-mode Voltage	-	-	1.9	-	V
I <sub>TX-SHORT</sub>	Transmitter Short-circuit Current Limit	-	-	20	60	mA
T <sub>ACTIVE</sub>	PD Low to CML Output Delay				200	ns
T <sub>POWERDOWN</sub>	PD High to CML Output High Fix Delay				10	ns
T <sub>SKEW</sub>	CML Output Inter-pair skew				25	ps
T <sub>PROPAGATION</sub>	Differential Propagation Delay	-	-	150	-	ps
ΔT <sub>PROPAGATION</sub>	Delta Propagation Delay				90	ps
T <sub>SWITCH</sub>	Switching Time	-	-	-	10	ns

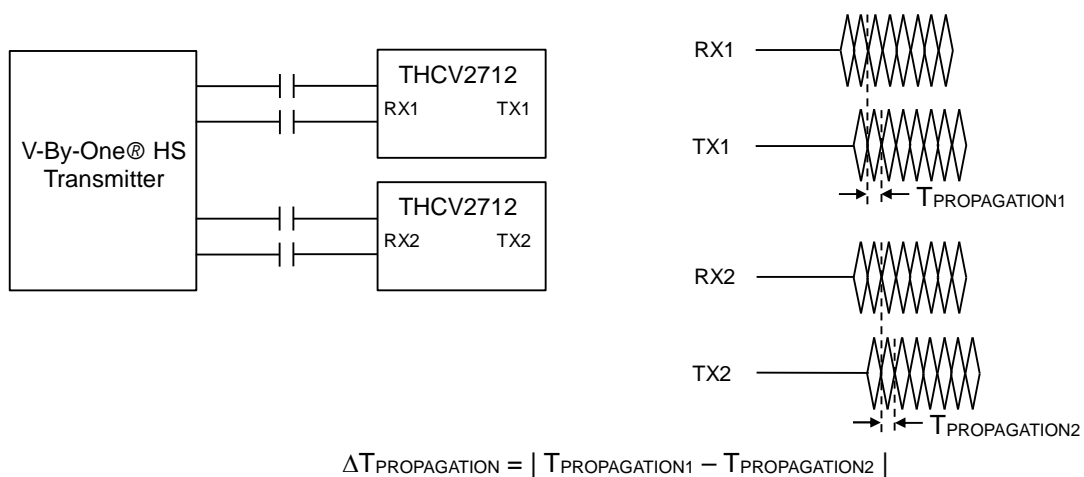


**Figure 3 Power on Sequence (Distribution Mode)**



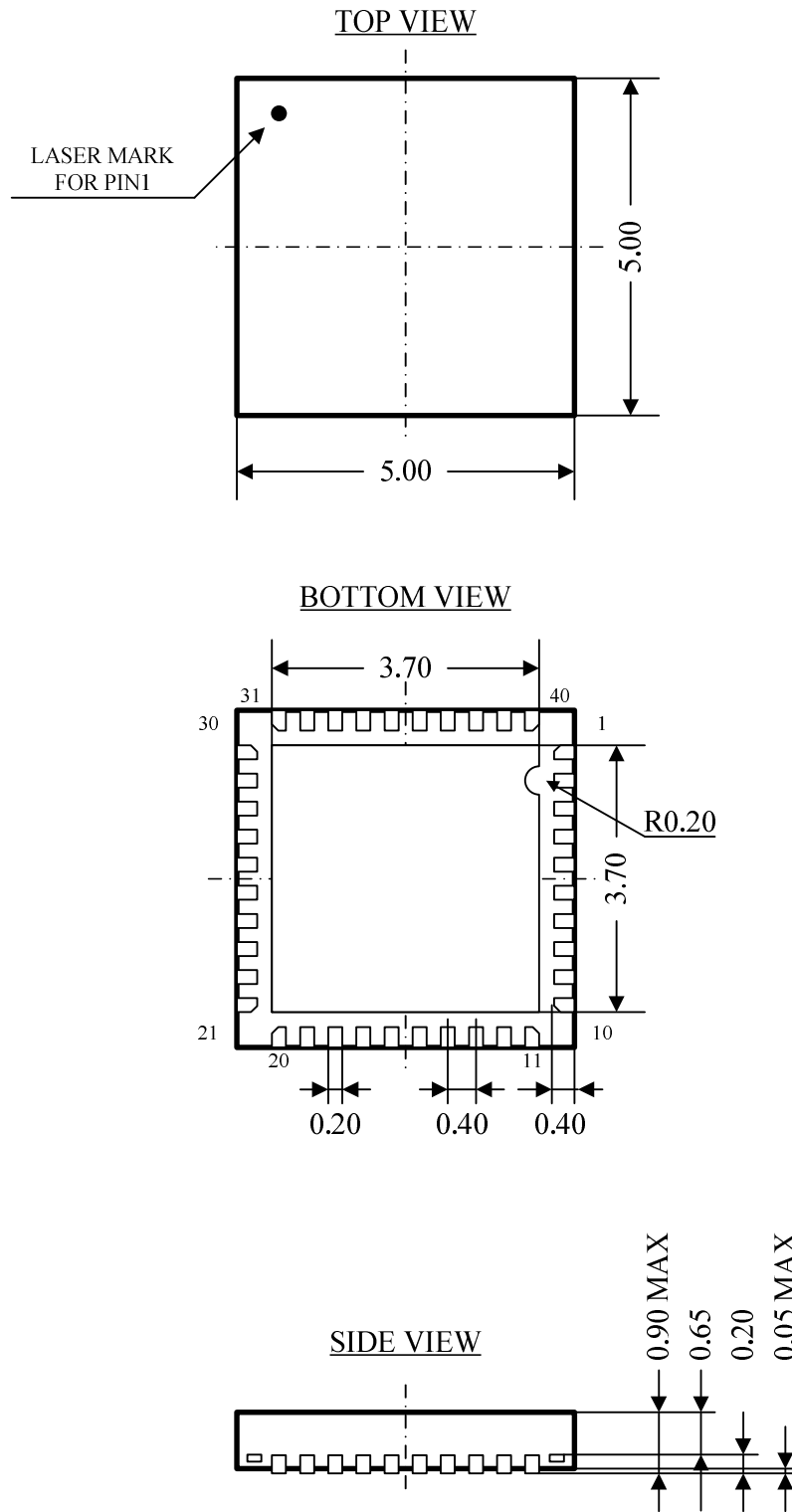


**Figure 4. Power on Sequence (Switch Mode)**



**Figure 5. CML Propagation Delay Timing**

**Package**



Unit : mm

**Figure 6. 40-pin QFN package physical dimension**

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7. Please note that this product is not designed to be radiation-proof.
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10. The product or peripheral parts may be damaged by a surge in voltage over the absolute maximum ratings or malfunction, if pins of the product are shorted by such as foreign substance. The damages may cause a smoking and ignition. Therefore, you are encouraged to implement safety measures by adding protection devices, such as fuses.

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